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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT application of:)
 Shunpei YAMAZAKI et al.) Examiner: F. Toledo
 Serial No. 09/352,194) Art Unit No. 2823
 Filed: July 13, 1999)
 For: CRYSTALLINE)
 SEMICONDUCTOR THIN FILM,)
 METHOD OF FABRICATING)
 THE SAME, SEMICONDUCTOR)
 DEVICE, AND METHOD OF)
 FABRICATING THE SAME) Date: January 29, 2001

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
 Washington, D.C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56 and 37 C.F.R. 1.97-1.99, it is requested that the references listed on the attached Form PTO-1449 be made of record in the above-identified application.

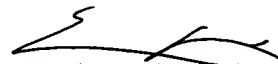
The Examiner's attention is directed to U.S. Patent No. 5,569,610, a copy of which is submitted herewith. In accordance with the provisions of 37 C.F.R. 1.56 and 37 C.F.R. 1.97-1.99, it is requested that the references listed on the Form PTO-1449 be made of record in the above-identified application.

Enclosed herewith is a check in the amount of \$180.00 for the statutory disclosure fee. The Commissioner is hereby authorized to charge fees under 37 C.F.R. 1.16 and 1.17 (except the Issue Fee) which may be required now or hereafter, or credit any overpayment, to Deposit Account No. 19-2380 (0756-1998).

A copy of the reference is submitted herewith in accordance with 37 C.F.R. 1.98(a). **A duplicate copy of this sheet is attached.**

The PTO did not receive the following
 listed item(s) a check for
\$ 180.00

Respectfully submitted,


 Eric J. Robinson
 Registration No. 38,285

EJR/CTB/lfm

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